

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application of :

Daisuke Nakamura et al :

Filed: Herewith :

For: HEAT DISSIPATING STRUCTURE OF PRINTED
CIRCUIT BOARD AND FABRICATING METHOD THEREOF

PRELIMINARY AMENDMENT A

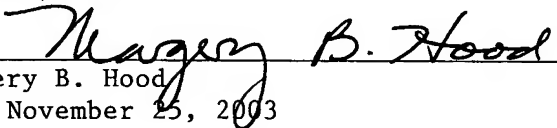
Director
U.S. Patent and Trademark Office
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please preliminarily amend the above-referenced application
as follows:

FILING OF PAPERS AND FEES BY "EXPRESS MAIL"
WITH CERTIFICATE IN ACCORDANCE WITH 37 CFR 1.10

I hereby certify that this correspondence is being
deposited with the United States Postal Service on
the date shown below with sufficient postage as "Express
Mail" in an envelope with Mailing Label No. EV303712989US
placed thereon prior to mailing and addressed to the
Director, U.S. Patent and Trademark Office, P.O. Box 1450,
Alexandria, VA 22313-1450.


Margery B. Hood

Dated: November 25, 2003